HT4500 Thermal Conductive Gap Filler

BENEFITS AND FEATURES

- One-part, pre-cured
- Low viscosity
- Dispensable and printable
- Reliable thermal performance
- No pump out and cracking risk

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Memory & power modules
- Power electronics

OVERVIEW

Honeywell HT4500 dispensable/printable gap filler is silicone-based and filled with advanced ceramic fillers. It is formulated to deliver high dispense rate for improved productivity, good gap filling ability under low pressure and low contamination to devices. The viscosity is modified for printing process. The material is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing.

STORAGE & USE

- Shelf life 6 months at -10~10°C, ⩽65% RH

Property	HT4500	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Color	Green	Visual
Thermal Conductivity (W/m·K)	4.5	ASTM D5470
Thermal Impedance (°C·In^2/W) (1mm@10psi, Typical Value)	0.33	ASTM D5470
Dispense Rate (g/min)	50	90psi, 30cc EFD syringe
Density(g/cm^3)	3.25	ASTM D792
Minimum BLT (μm)	60	HON Internal
Dielectric Strength (KV/mm)	6	ASTM D149
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593

DS.0318Rev3